

Description

The GM76C512/L/LL is a 524,288 bits static random access memory organized as 65,536 words by 8 bits. Using a 0.8 μ m advanced CMOS technology, it provides high speed operation with minimum cycle time of 55/70/85/100ns. The device is placed in a low power standby mode with $\overline{CS1}$ high or CS2 low and the output enable ($\overline{OE}$) allows fast memory access. Thus it is suitable for high speed and low power applications, especially where battery back-up is required. The GM76C512/L/LL is offered in a 32-pin DIP (600mil), SOP (525 mil) and TSOP I (0820).

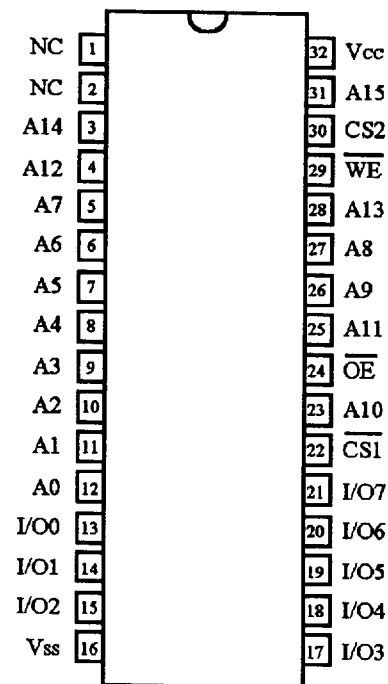
Features

- Fast Access and Cycle Time : 55/70/85ns Max.
- Low Power Standby and Low Power Operation
Standby : 5.5mW Max.
Standby : 0.55mW Max. (L - Version)
Standby : 0.165mW Max. (LL - Version)
Operation : 385mW Max.
- Completely Static RAM : No Clock or Timing Strobe Required
- Equal Access and Cycle Time
- Capability of Battery Back-up Operation
- Single + 5V Operation ($\pm 10\%$)
- Standard 32 DIP, SOP and TSOP I

Pin Description

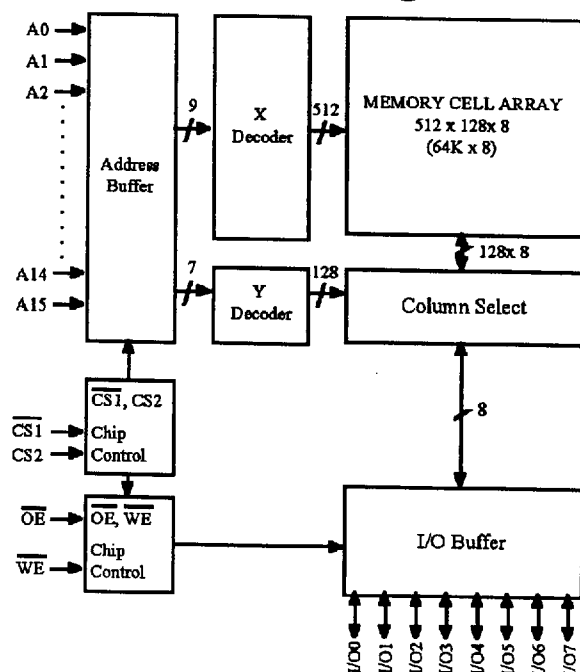
Pin	Function
A0-A15	Address Inputs
$\overline{WE}$	Write Enable Input
$\overline{CS1}$, CS2	Chip Select Input
$\overline{OE}$	Output Enable Input
I/O0-I/O7	Data Inputs/Outputs
Vcc	Power Supply (+5V)
Vss	Ground
NC	No Connection

Pin Configuration



(Top View)

Block Diagram



Absolute Maximum Ratings*

Symbol	Parameter	Rating	Unit
T_A	Ambient Temperature under Bias	0 ~ 70	°C
T_{STG}	Storage Temperature	-55 ~ 150	°C
T_{SOL}	Soldering Temperature and Time	260, 10 (at lead)	°C, s
V_{CC}	Supply Voltage	-0.3 ~ 7.0	V
V_{IN}	Input Voltage	-0.3* ~ 7.0	V
V_{IO}	Input and Output Voltage	-0.5 ~ $V_{CC} + 0.5$	V
P_D	Power Dissipation	1.0	W

*: -3.0V at pulse width 50ns Max.

Recommended Operating Conditions ($T_A = 0 \sim 70^\circ\text{C}$)

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.5	5.0	5.5	V
V_{IH}	Input High Voltage	2.2	-	$V_{CC} + 0.3$	V
V_{IL}	Input Low Voltage	-0.3	-	0.8	V

Truth Table

$\overline{CS1}$	$CS2$	$\overline{OE}$	$\overline{WE}$	A1 to A16	DATA I/O	MODE
L	H	L	H	Stable	Output Data	Read
L	H	X	L	Stable	Input Data	Write
L	H	H	H	Stable	Hi-Z	Output Disable
H	X	X	X	-	Hi-Z	Standby
X	L	X	X	-	Hi-Z	

*Note: X means "don't care".

DC Electrical Characteristics ($V_{CC} = 5V \pm 10\%$, $T_A = 0 \sim 70^\circ C$)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{I(L)}$	Input Leakage Current	$V_{IN} = 0 \text{ to } V_{CC}$	-1	-	1	μA
$I_{O(L)}$	Output Leakage Current	$\overline{CS1} = V_{IH} \text{ or } CS2 = V_{IL}$ $OE = V_{IH}, V_{SS} \leq V_{OUT} \leq V_{CC}$	-1	-	1	μA
I_{OH}	High Level Output Current	$V_{ON} = 2.4V$	-1.0	-	-	mA
I_{OL}	Low Level Output Current	$V_{ON} = 0.4V$	-	-	2.1	mA
I_{CC}	Operating Supply Current	$\overline{CS1} = V_{IL} \text{ or } CS2 = V_{IH}$ $V_{IN} = V_{IH}/V_{IL}, I_{OUT} = 0mA$	-	-	45	mA
I_{CC1}	Average Operating Current	$\overline{CS1} = V_{IL} \text{ and } CS2 = V_{IH}$ $V_{IN} = V_{IH}/V_{IL}$ $I_{OUT} = 0mA$ $t_{cycle} = \text{Min, cycle}$	-	-	70	mA
I_{CC2}		$\overline{CS1} = 0.2V, CS2 = V_{CC}-0.2V$ $V_{IN} = V_{CC}-0.2V/0.2V$ $I_{OUT} = 0mA$ $t_{cycle} = 1\mu s$	-	-	45	mA
I_{CCS1}	Standby Current	$\overline{CS1} = V_{IH} \text{ or } CS2 = V_{IL}$	-	-	2	mA
I_{CCS2}		$\overline{CS1} = V_{CC}-0.2V, CS2 = 0.2V$	-	-	1	mA
		GM76C512	-	-	2*	100
		GM76C512L	-	-	2*	30
		GM76C512LL	-	-	2*	30

*TYP. Values are measured at $25^\circ C$, $V_{CC} = 5V$

AC Operating Characteristics ($V_{CC} = 5V \pm 10\%$, $T_A = 0 \sim 70^\circ C$)

Read Cycle

Symbol	Parameter	GM76C512-55		GM76C512-70		GM76C512-85		GM76C512-10		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{RC}	Read Cycle Time	55	-	70	-	85	-	100	-	ns
t_{AA}	Address Access Time	-	55	-	70	-	85	-	100	ns
t_{ACS1}	Chip Select 1 Access Time	-	55	-	70	-	85	-	100	ns
t_{ACS2}	Chip Select 2 Access Time	-	55	-	70	-	85	-	100	ns
t_{OE}	Output Enable Access Time	-	25	-	30	-	45	-	50	ns
t_{CLZ1}	Chip Select 1 Output Setup Time	10	-	10	-	10	-	10	-	ns
t_{CHZ1}	Chip Select 1 Output Floating	-	20	-	25	-	30	-	35	ns
t_{CLZ2}	Chip Select 2 Output Setup Time	10	-	10	-	10	-	10	-	ns
t_{CHZ2}	Chip Select 2 Output Floating	-	20	-	25	-	30	-	35	ns
t_{OLZ}	Output Enable Output Setup Time	0	-	0	-	0	-	0	-	ns
t_{OHZ}	Output Enable Output Floating	-	20	-	25	-	30	-	35	ns
t_{OH}	Output Hold Time	10	-	10	-	10	-	10	-	ns

Write Cycle

Symbol	Parameter	GM76C512-55		GM76C512-70		GM76C512-85		GM76C512-10		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{WC}	Write Cycle Time	55	-	70	-	85	-	100	-	ns
t_{CW1}	Chip Select Time 1	45	-	60	-	70	-	80	-	ns
t_{CW2}	Chip Select Time 2	45	-	60	-	70	-	80	-	ns
t_{AW}	Address Enable Time	50	-	60	-	70	-	80	-	ns
t_{AS}	Address Set-up Time	0	-	0	-	0	-	0	-	ns
t_{WP}	Write Pulse Width	40	-	50	-	60	-	60	-	ns
t_{WR}	Address Hold Time	0	-	0	-	0	-	0	-	ns
t_{DW}	Input Data Setup Time	25	-	30	-	35	-	40	-	ns
t_{DH}	Input Data Hold Time	0	-	0	-	0	-	0	-	ns
t_{WHZ}	Write to Output in Hihg-Z	-	20	-	25	-	30	-	35	ns
t_{OW}	Output Active from End of Write	0	-	0	-	0	-	0	-	ns

AC TEST CONDITIONS

- Output load : 100pF + 1TTL Gate

- Input pulse level : 0.6V to 2.4V

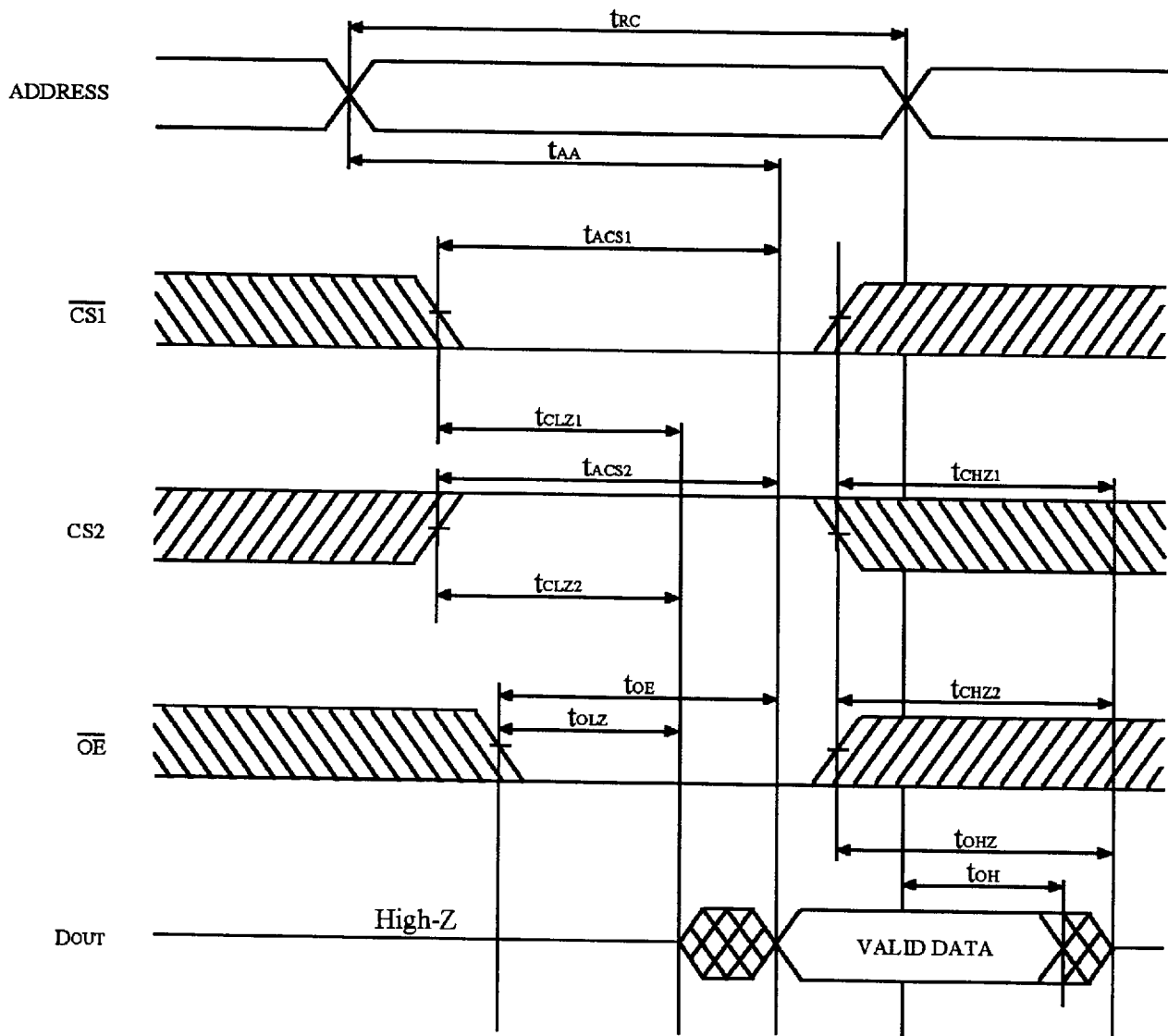
- Input and output timing reference levels : 1.5V

- $t_r = t_f = 5ns$

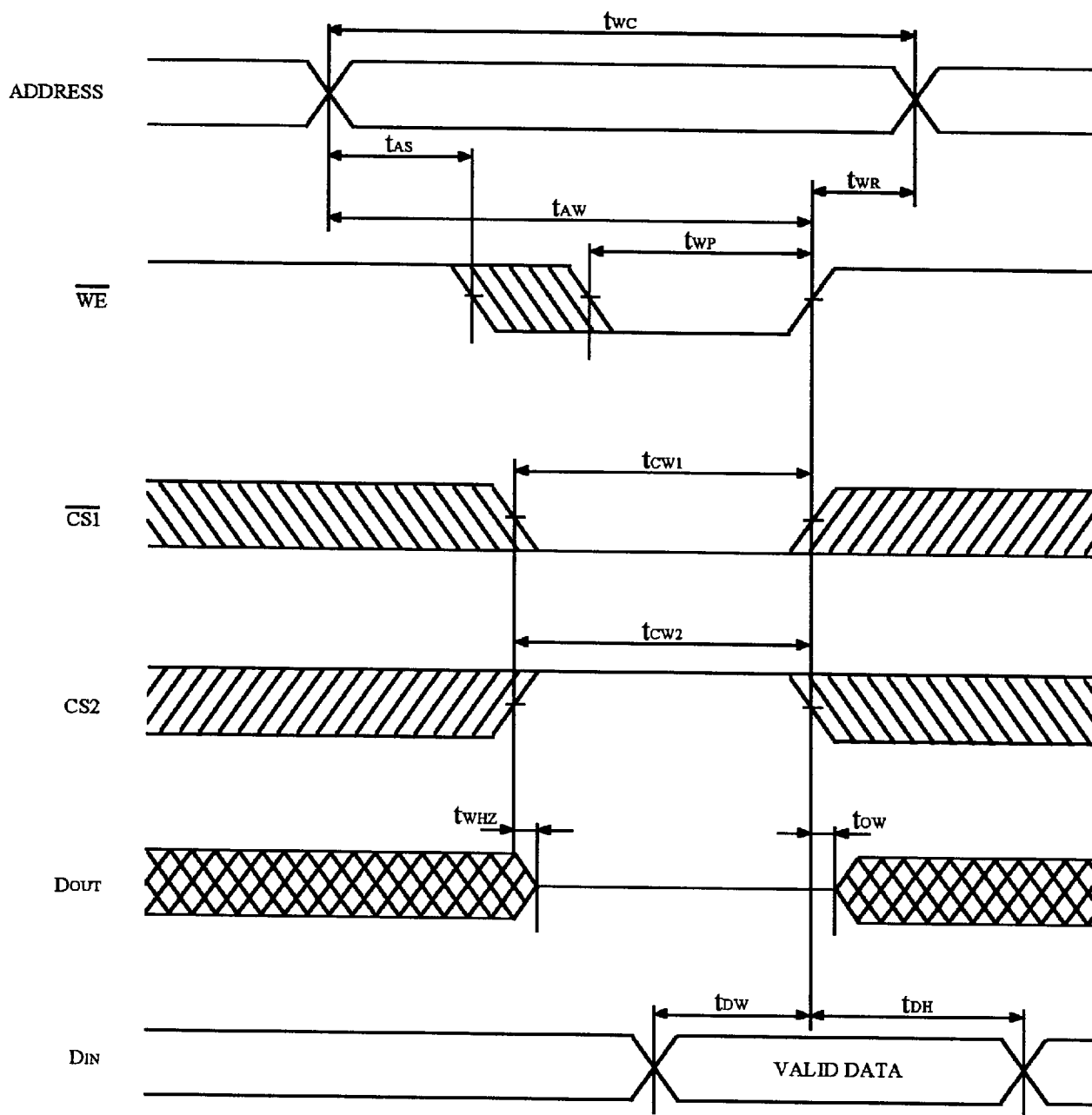


Timing Waveforms

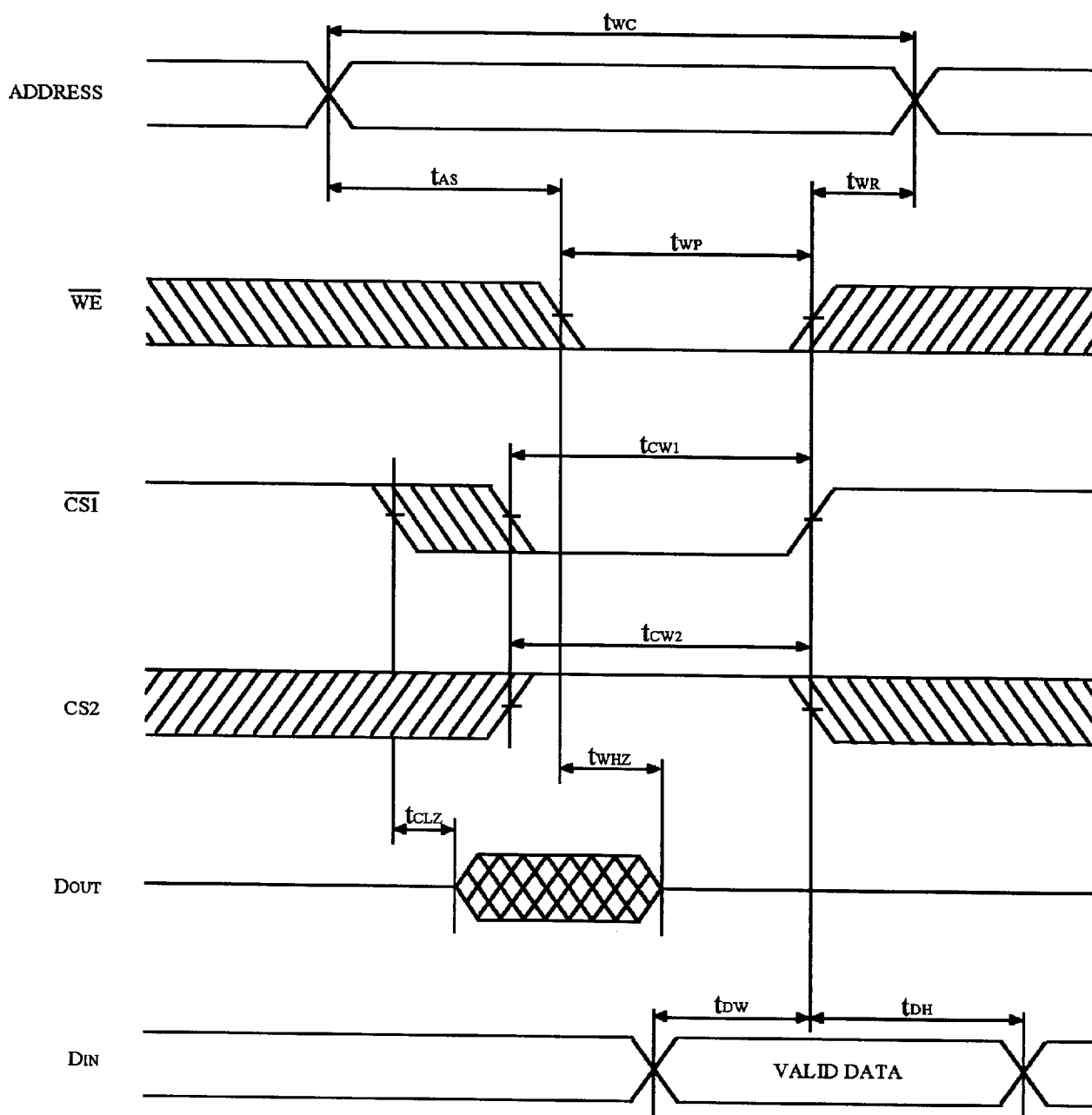
Read Cycle (Note 1)



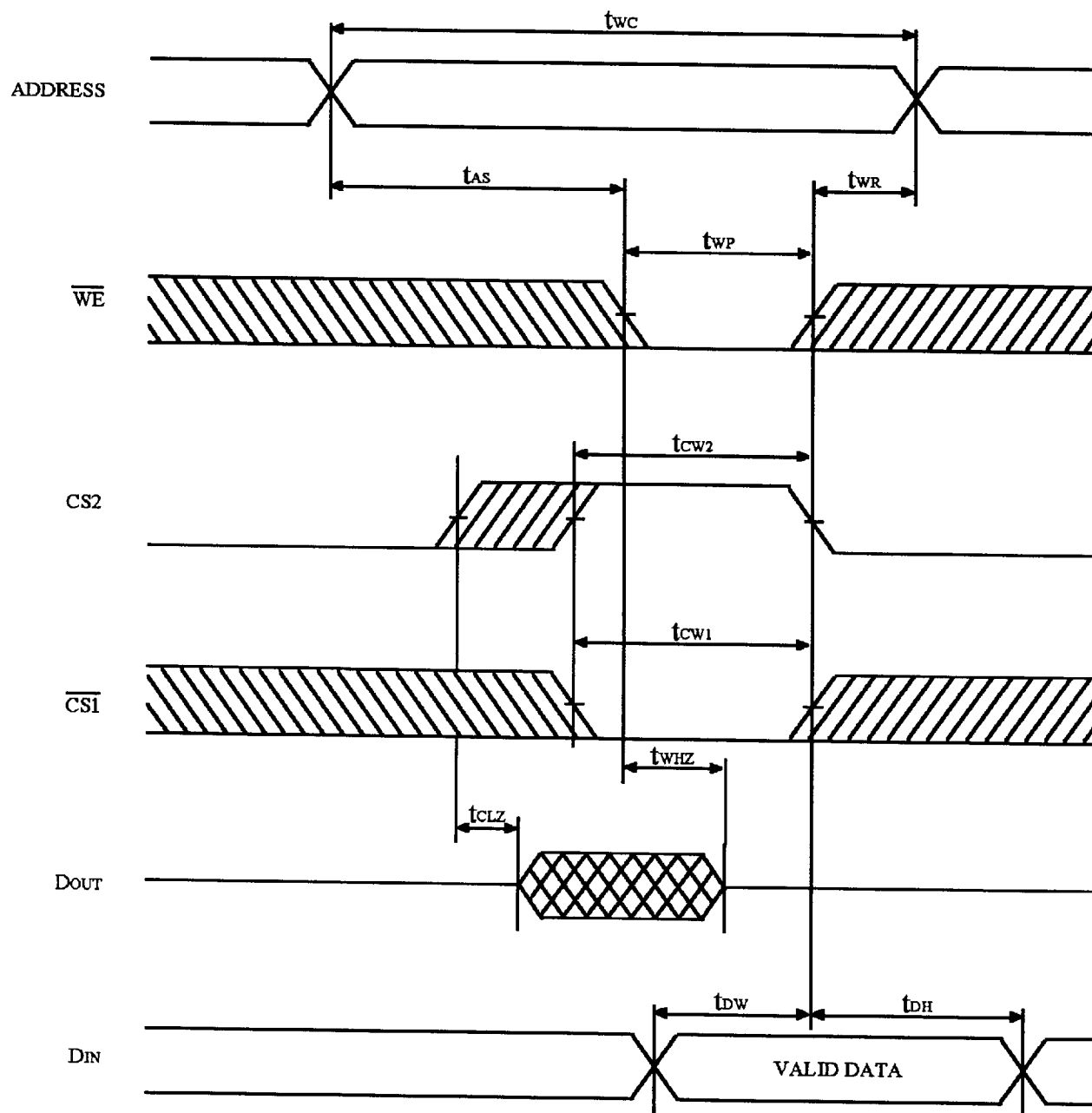
Write Cycle (1) ($\overline{\text{WE}}$ Controlled) (Notes 2, 3, 4)



Write Cycle (2) ($\overline{\text{CS1}}$ Controlled) (Notes 4)



Write Cycle (3) (CS2 Controlled) (Notes 4)



Notes:

1. $\overline{WE}$ is High for Read Cycle.
2. Assuming that $\overline{CS1}$ Low transition or CS2 High transition occurs coincident with or after $\overline{WE}$ Low transition. Outputs remain in a high impedance state.
3. Assuming that $\overline{CS1}$ High transition or CS2 Low transition occurs coincident with or prior to $\overline{WE}$ High transition. Outputs remain in a high impedance state.
4. Assuming that $\overline{OE}$ is high for write cycle. Outputs are in a high impedance state during this period.

Capacitance ($f = 1\text{MHz}$, $T_A = 25^\circ\text{C}$)

Symbol	Parameter	Test Conditions	Min	Max	Unit
C_{IN}	Input Capacitance	$V_I = 0\text{V}$	-	8	pF
C_{OUT}	Output Capacitance	$V_O = 0\text{V}$	-	8	pF

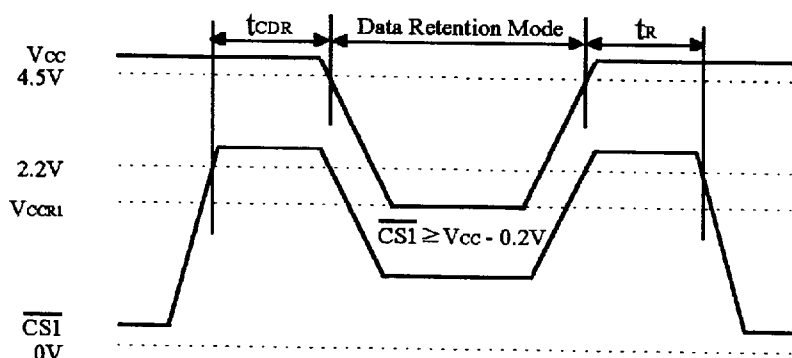
*Note: This parameter is sampled and not 100% tested.

Data Retention Characteristics ($T_A = 0 \sim 70^\circ\text{C}$)

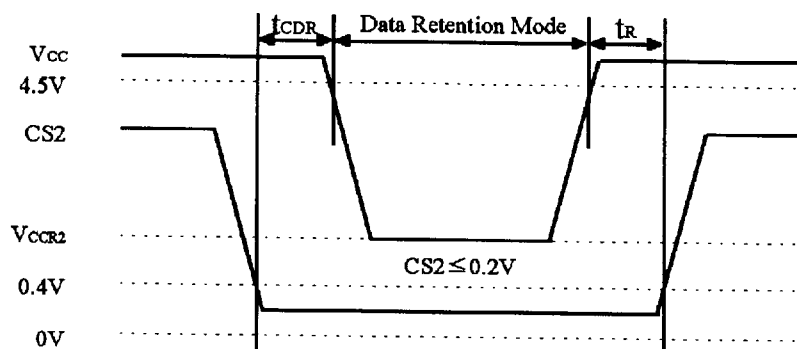
Symbol	Parameter			Min	Typ	Max	Unit
V _{CCR}	Data Retention Supply Voltage			2.0	-	5.5	V
I _{CCR}	Data Retention Current	V _{CC} = 3.0V	L	-	1	50*	μA
			LL	-	1	25	
t _{CDR}	Chip Select to Data Retention Time			0	-	-	ns
t _R	Operation Recovery Time			5	-	-	ns

*20 μA max at $T_A = 0 \sim 40^\circ\text{C}$...

• **Low V_{CC} Data Retention Mode: (1) $\overline{\text{CS1}}$ Controlled**



• **Low V_{CC} Data Retention Mode: (2) CS2 Controlled**

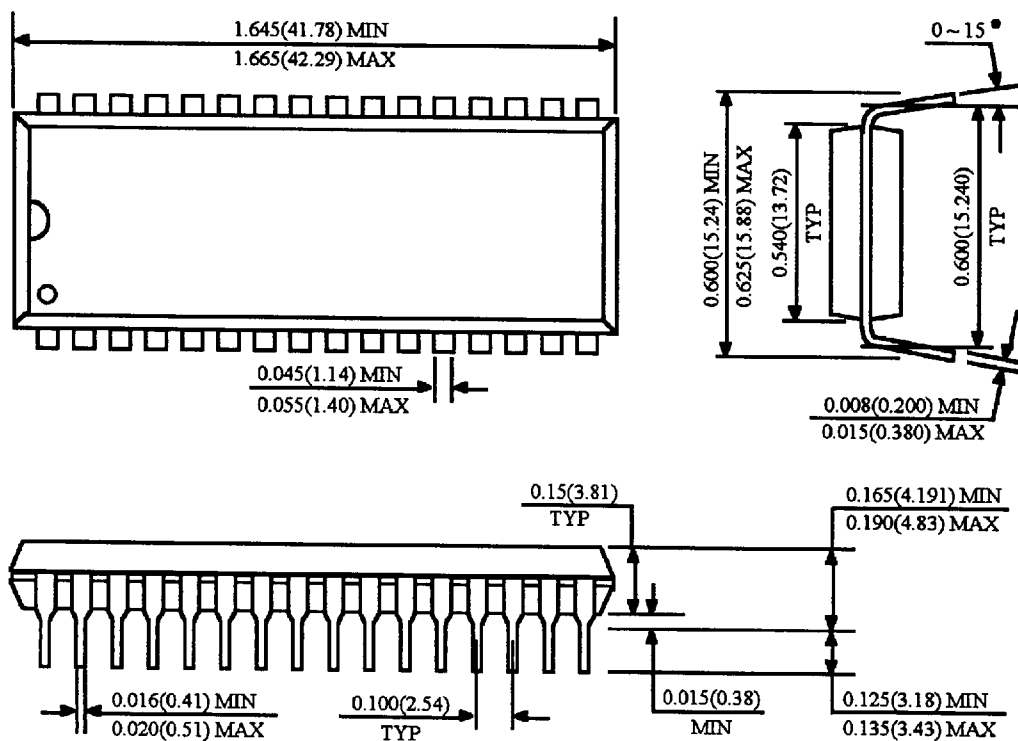


Notes: In Data Retention Mode, CS2 controls the Address, $\overline{\text{WE}}$, $\overline{\text{CS1}}$, $\overline{\text{OE}}$ and D_{IN} buffer. If CS2 controls data retention mode, V_{IN} for these inputs can be in the high impedance state. If $\overline{\text{CS1}}$ controls the data retention mode, CS2 must satisfy either $\text{CS2} \geq V_{CC} - 0.2\text{V}$ or $\text{CS2} \leq 0.2\text{V}$. The other input levels (Address, $\overline{\text{WE}}$, $\overline{\text{OE}}$, I/O) can be in the high impedance state.

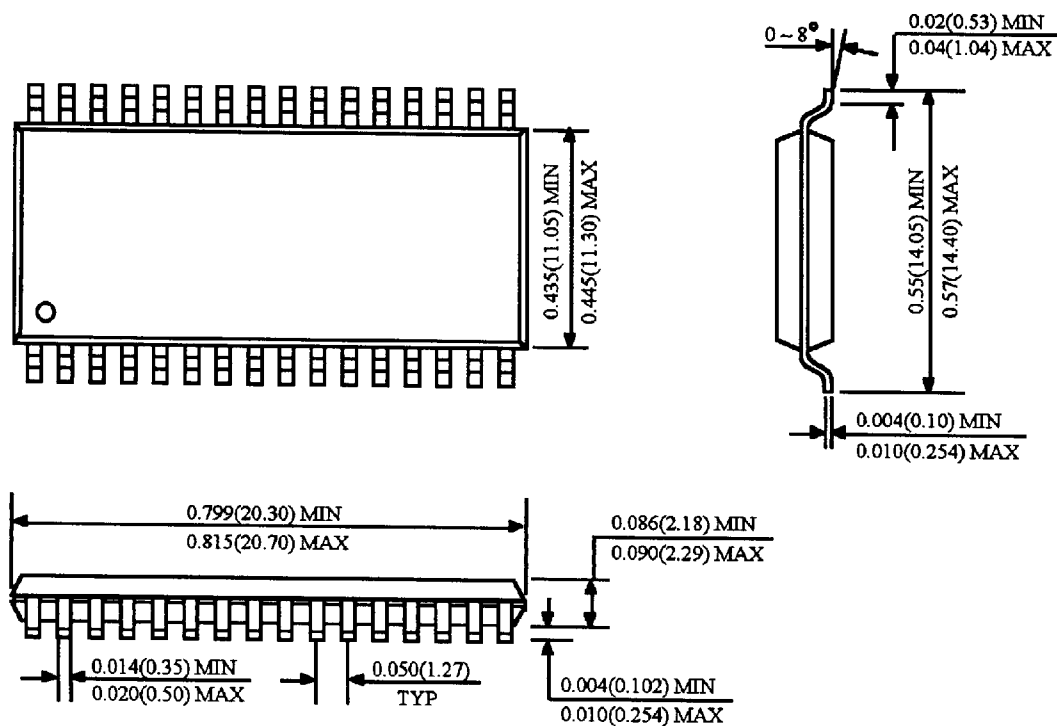
Package Dimensions

Unit: Inches (mm)

32 DIP - A



32 SOP - A



Unit: Inches (mm)

32 TSOP I

